

## Surface-Mount Schottky Barrier Rectifier

### eSMP® Series



Top view

Bottom view

### SMF (DO-219AB)

 Cathode  Anode

### LINKS TO ADDITIONAL RESOURCES


[3D Models](#)

### PRIMARY CHARACTERISTICS

$I_{F(AV)}$	1.0 A
$V_{RRM}$	60 V
$I_{FSM}$	40 A
$V_F$ at $I_F = 1.0$ A ( $T_A = 125$ °C)	0.38 V
$T_J$ max. (AC mode)	150 °C
$T_J$ max. (DC forward current)	175 °C
Package	SMF (DO-219AB)
Circuit configuration	Single

### FEATURES

- Low profile package
- Ideal for automated placement
- Low forward voltage drop, low power losses
- Low leakage current
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- Wave and reflow solderable
- AEC-Q101 qualified
  - Automotive ordering code: base P/NHM3
- Compatible to SOD-123W package case outline
- Material categorization: for definitions of compliance please see [www.vishay.com/doc?99912](http://www.vishay.com/doc?99912)


**RoHS**  
 COMPLIANT  
 HALOGEN  
**FREE**

### TYPICAL APPLICATIONS

For use in high frequency inverters, freewheeling, DC/DC converters, and polarity protection in commercial, industrial, and automotive applications.

### MECHANICAL DATA

#### Case: SMF (DO-219AB)

Molding compound meets UL 94 V-0 flammability rating

Base P/N-M3 - halogen-free, RoHS-compliant

Base P/NHM3 - halogen-free, RoHS-compliant, and AEC-Q101 qualified

**Terminals:** matte tin plated leads, solderable per J-STD-002 and JESD 22-B102

M3 and HM3 suffix meets JESD 201 class 2 whisker test

**Polarity:** color band denotes the cathode end

### MAXIMUM RATINGS ( $T_A = 25$ °C unless otherwise noted)

PARAMETER	SYMBOL	SS1FN6	UNIT
Device marking code		1N6	
Maximum repetitive peak reverse voltage	$V_{RRM}$	60	V
Maximum average forward rectified current (fig. 1)	$I_{F(AV)}$ <sup>(1)</sup>	1.0	A
Non-repetitive peak forward surge current 8.3 ms single half sine-wave at $T_{J(init)} = 25$ °C	$I_{FSM}$	40	A
Operating junction and storage temperature range	$T_J, T_{STG}$	-55 to +150	°C
Junction temperature in DC forward current without reverse bias	$T_J$	+175	°C

#### Note

<sup>(1)</sup> Free air, mounted on recommended copper pad area



<b>ELECTRICAL CHARACTERISTICS</b> ( $T_A = 25\text{ }^\circ\text{C}$ unless otherwise noted)						
PARAMETER	TEST CONDITIONS		SYMBOL	TYP.	MAX.	UNIT
Instantaneous forward voltage	$I_F = 0.7\text{ A}$	$T_A = 25\text{ }^\circ\text{C}$	$V_F^{(1)}$	0.42	-	V
	$I_F = 1.0\text{ A}$			0.45	0.53	
	$I_F = 0.7\text{ A}$	$T_A = 125\text{ }^\circ\text{C}$		0.33	-	
	$I_F = 1.0\text{ A}$			0.38	0.46	
Reverse current	$V_R = 60\text{ V}$	$T_A = 25\text{ }^\circ\text{C}$	$I_R^{(2)}$	-	800	$\mu\text{A}$
		$T_A = 125\text{ }^\circ\text{C}$		12	35	mA
Typical junction capacitance	4.0 V, 1 MHz		$C_J$	90	-	pF

**Notes**

- (1) Pulse test: 300  $\mu\text{s}$  pulse width, 1 % duty cycle  
(2) Pulse test: Pulse width  $\leq 5\text{ ms}$

<b>THERMAL CHARACTERISTICS</b> ( $T_A = 25\text{ }^\circ\text{C}$ unless otherwise noted)			
PARAMETER	SYMBOL	SS1FN6	UNIT
Typical thermal resistance	$R_{\theta JA}^{(1)(2)(3)}$	125	$^\circ\text{C/W}$
	$R_{\theta JM}^{(2)(3)}$	15	

**Notes**

- (1) The heat generated must be less than the thermal conductivity from junction-to-ambient:  $dP_D/dT_J < 1/R_{\theta JA}$   
(2) Device mounted on FR4 PCB, 2 oz. standard footprint  
(3) Thermal resistance  $R_{\theta JA}$  - junction to ambient;  $R_{\theta JM}$  - junction to mount

<b>ORDERING INFORMATION</b> (Example)				
PREFERRED P/N	UNIT WEIGHT (g)	PREFERRED PACKAGE CODE	BASE QUANTITY	DELIVERY MODE
SS1FN6-M3/H	0.015	H	3000	7" diameter plastic tape and reel
SS1FN6-M3/I	0.015	I	10 000	13" diameter plastic tape and reel
SS1FN6HM3/H <sup>(1)</sup>	0.015	H	3000	7" diameter plastic tape and reel
SS1FN6HM3/I <sup>(1)</sup>	0.015	I	10 000	13" diameter plastic tape and reel

**Note**

- (1) AEC-Q101 qualified

**RATINGS AND CHARACTERISTICS CURVES** ( $T_A = 25\text{ }^\circ\text{C}$  unless otherwise noted)

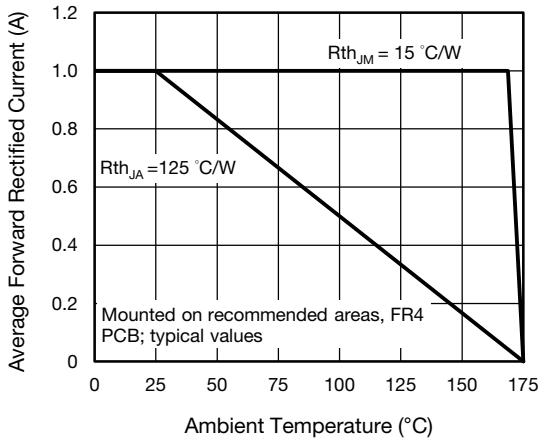


Fig. 1 - Typical Forward Current Derating Curve

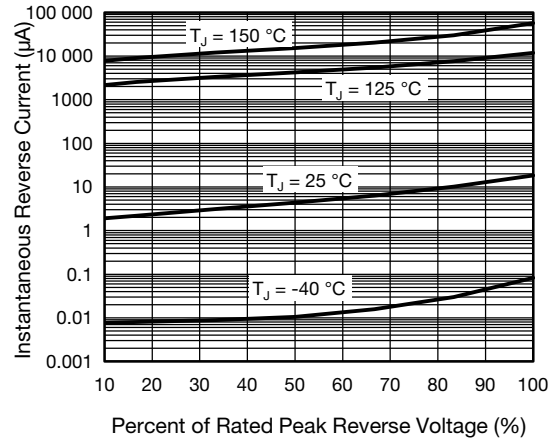


Fig. 4 - Typical Reverse Leakage Characteristics

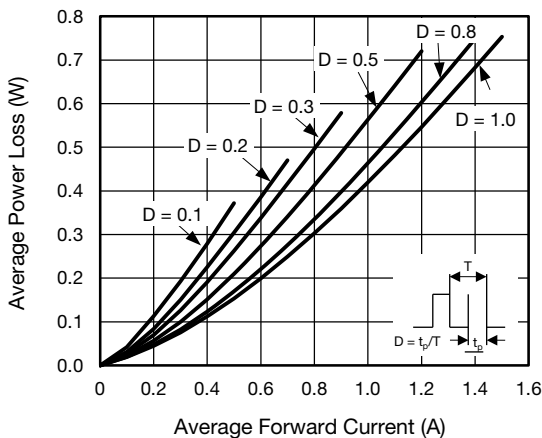


Fig. 2 - Forward Power Loss Characteristics

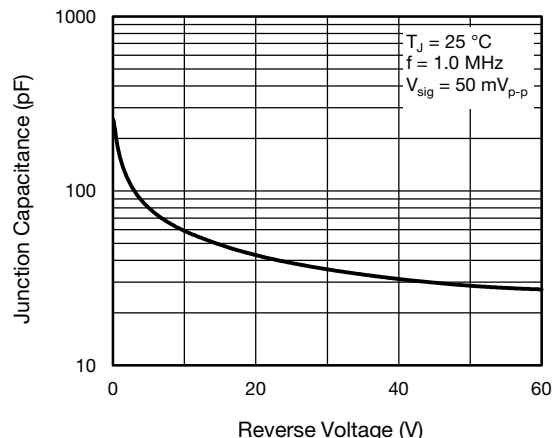


Fig. 5 - Typical Junction Capacitance

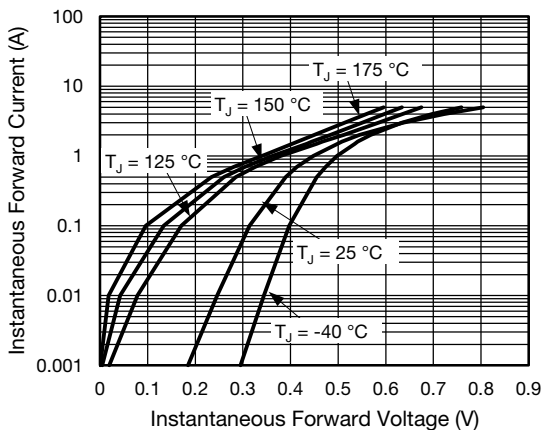


Fig. 3 - Typical Instantaneous Forward Characteristics

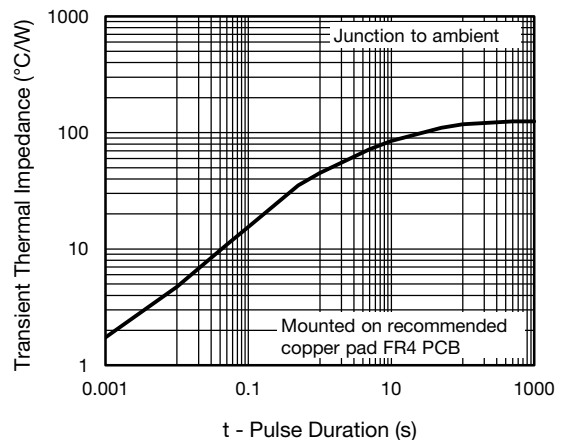
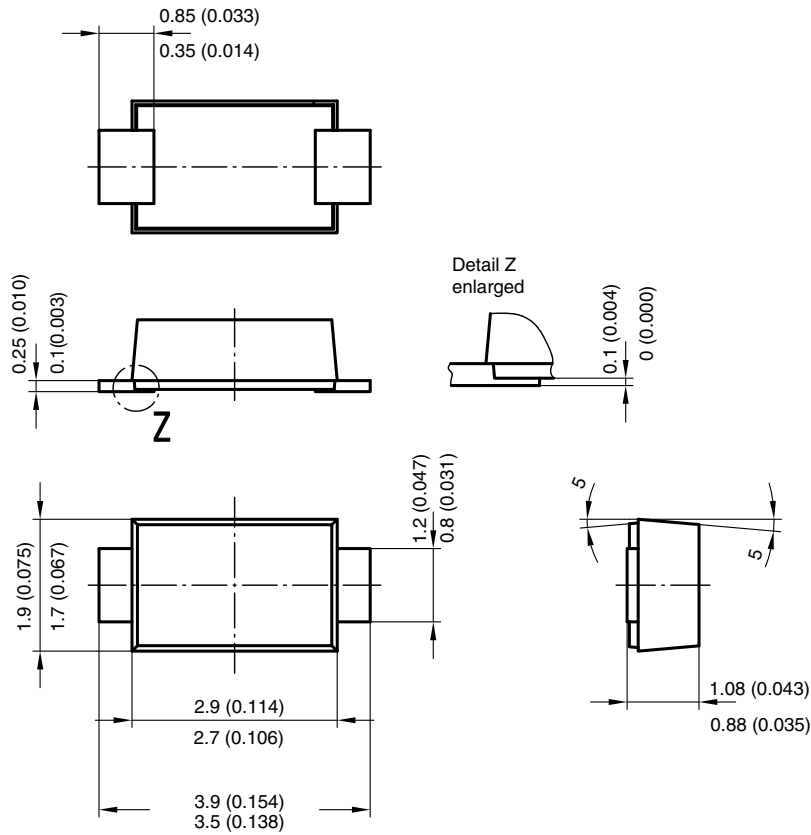
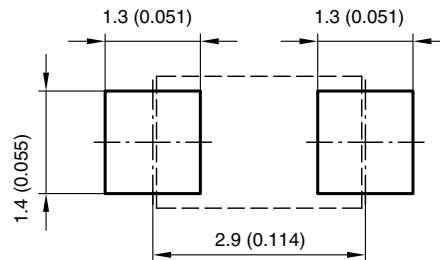


Fig. 6 - Typical Transient Thermal Impedance

**PACKAGE OUTLINE DIMENSIONS** in millimeters (inches): **SMF (DO-219AB)**



Foot print recommendation:



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 17247



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